

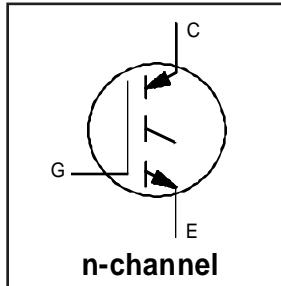
# IRGBC30K-S

INSULATED GATE BIPOLAR TRANSISTOR

Short Circuit Rated  
UltraFast Fast IGBT

## Features

- Short circuit rated - 10 $\mu$ s @ 125°C, V<sub>GE</sub> = 15V
- Switching-loss rating includes all "tail" losses
- Optimized for high operating frequency (over 5kHz)  
See Fig. 1 for Current vs. Frequency curve

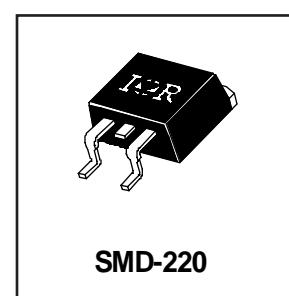


V<sub>CES</sub> = 600V  
V<sub>CE(sat)</sub> ≤ 3.8V  
@ V<sub>GE</sub> = 15V, I<sub>C</sub> = 14A

## Description

Insulated Gate Bipolar Transistors (IGBTs) from International Rectifier have higher usable current densities than comparable bipolar transistors, while at the same time having simpler gate-drive requirements of the familiar power MOSFET. They provide substantial benefits to a host of high-voltage, high-current applications.

These new short circuit rated devices are especially suited for motor control and other applications requiring short circuit withstand capability.



## Absolute Maximum Ratings

	Parameter	Max.	Units
V <sub>CES</sub>	Collector-to-Emitter Voltage	600	V
I <sub>C</sub> @ T <sub>C</sub> = 25°C	Continuous Collector Current	23	
I <sub>C</sub> @ T <sub>C</sub> = 100°C	Continuous Collector Current	14	A
I <sub>CM</sub>	Pulsed Collector Current ①	46	
I <sub>LM</sub>	Clamped Inductive Load Current ②	46	
t <sub>sc</sub>	Short Circuit Withstand Time	10	$\mu$ s
V <sub>GE</sub>	Gate-to-Emitter Voltage	±20	V
E <sub>ARV</sub>	Reverse Voltage Avalanche Energy ③	10	mJ
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Maximum Power Dissipation	100	
P <sub>D</sub> @ T <sub>C</sub> = 100°C	Maximum Power Dissipation	42	W
T <sub>J</sub>	Operating Junction and	-55 to +150	
T <sub>STG</sub>	Storage Temperature Range		°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting torque, 6-32 or M3 screw.	10 lbf·in (1.1N·m)	

## Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
R <sub>θJC</sub>	Junction-to-Case	—	—	1.2	°C/W
R <sub>θJA</sub>	Junction-to-Ambient, (PCB mount)**	—	—	40	
R <sub>θJA</sub>	Junction-to-Ambient, typical socket mount	—	—	80	
Wt	Weight	—	2 (0.07)	—	g (oz)

\*\* When mounted on 1" square PCB (FR-4 or G-10 Material)

For recommended footprint and soldering techniques refer to application note #AN-994.

**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

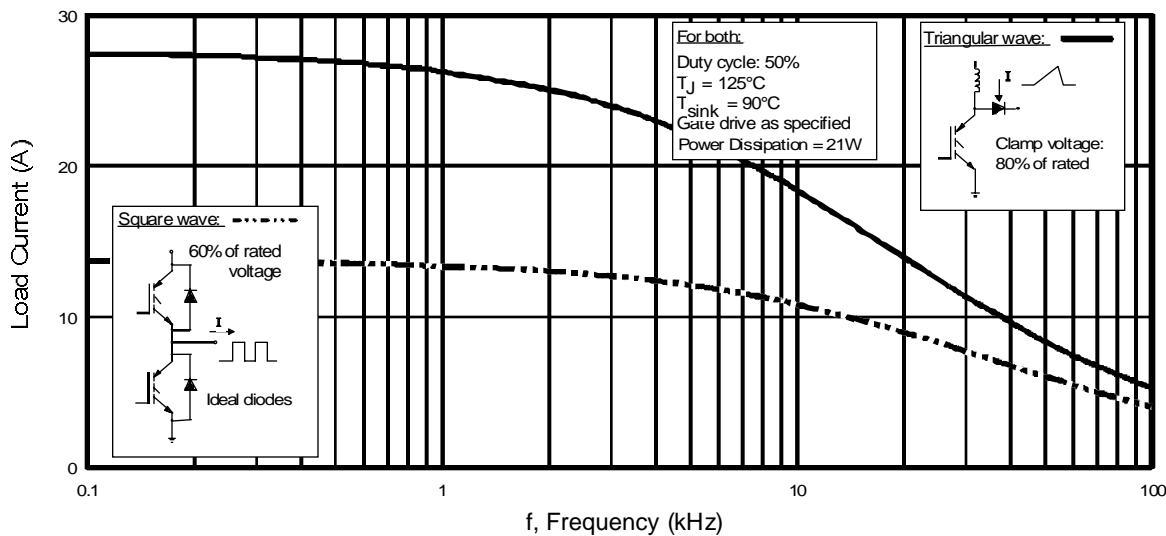
	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{CES}}$	Collector-to-Emitter Breakdown Voltage	600	—	—	V	$V_{\text{GE}} = 0\text{V}, I_C = 250\mu\text{A}$
$V_{(\text{BR})\text{ECS}}$	Emitter-to-Collector Breakdown Voltage ④	20	—	—	V	$V_{\text{GE}} = 0\text{V}, I_C = 1.0\text{A}$
$\Delta V_{(\text{BR})\text{CES}/\Delta T_J}$	Temperature Coeff. of Breakdown Voltage	—	0.45	—	$\text{V}^\circ\text{C}$	$V_{\text{GE}} = 0\text{V}, I_C = 1.0\text{mA}$
$V_{\text{CE}(\text{on})}$	Collector-to-Emitter Saturation Voltage	—	2.2	3.3	V	$I_C = 14\text{A} \quad V_{\text{GE}} = 15\text{V}$
		—	2.9	—		$I_C = 23\text{A} \quad \text{See Fig. 2, 5}$
		—	2.5	—		$I_C = 14\text{A}, T_J = 150^\circ\text{C}$
		3.0	—	5.5		$V_{\text{CE}} = V_{\text{GE}}, I_C = 250\mu\text{A}$
$\Delta V_{\text{GE}(\text{th})}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-13	—	$\text{mV}^\circ\text{C}$	$V_{\text{CE}} = V_{\text{GE}}, I_C = 250\mu\text{A}$
$g_{\text{fe}}$	Forward Transconductance ⑤	3.0	6.0	—	S	$V_{\text{CE}} = 100\text{V}, I_C = 14\text{A}$
$I_{\text{CES}}$	Zero Gate Voltage Collector Current	—	—	600	$\mu\text{A}$	$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}$
		—	—	1100		$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}, T_J = 150^\circ\text{C}$
$I_{\text{GES}}$	Gate-to-Emitter Leakage Current	—	—	$\pm 100$	nA	$V_{\text{GE}} = \pm 20\text{V}$

**Switching Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

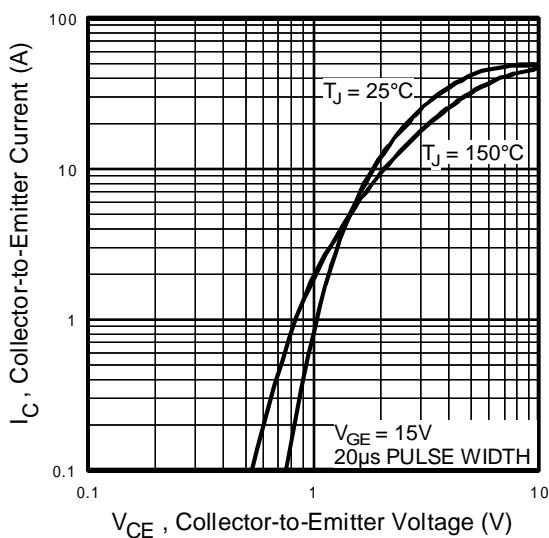
	Parameter	Min.	Typ.	Max.	Units	Conditions
$Q_g$	Total Gate Charge (turn-on)	—	39	58	nC	$I_C = 14\text{A}$ $V_{\text{CC}} = 400\text{V}$ See Fig. 8 $V_{\text{GE}} = 15\text{V}$
$Q_{ge}$	Gate - Emitter Charge (turn-on)	—	8.7	13		
$Q_{gc}$	Gate - Collector Charge (turn-on)	—	15	23		
$t_{d(\text{on})}$	Turn-On Delay Time	—	31	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 14\text{A}, V_{\text{CC}} = 480\text{V}$ $V_{\text{GE}} = 15\text{V}, R_G = 23\Omega$ Energy losses include "tail"
$t_r$	Rise Time	—	23	—		
$t_{d(\text{off})}$	Turn-Off Delay Time	—	100	150		
$t_f$	Fall Time	—	84	130		
$E_{\text{on}}$	Turn-On Switching Loss	—	0.3	—	mJ	See Fig. 9, 10, 11, 14
$E_{\text{off}}$	Turn-Off Switching Loss	—	0.3	—		
$E_{ts}$	Total Switching Loss	—	0.6	0.9		
$t_{sc}$	Short Circuit Withstand Time	10	—	—	$\mu\text{s}$	$V_{\text{CC}} = 360\text{V}, T_J = 125^\circ\text{C}$ $V_{\text{GE}} = 15\text{V}, R_G = 23\Omega, V_{\text{CPK}} < 500\text{V}$
$t_{d(\text{on})}$	Turn-On Delay Time	—	30	—	ns	$T_J = 150^\circ\text{C},$ $I_C = 14\text{A}, V_{\text{CC}} = 480\text{V}$ $V_{\text{GE}} = 15\text{V}, R_G = 23\Omega$ Energy losses include "tail"
$t_r$	Rise Time	—	23	—		
$t_{d(\text{off})}$	Turn-Off Delay Time	—	170	—		
$t_f$	Fall Time	—	170	—		
$E_{ts}$	Total Switching Loss	—	1.2	—	mJ	See Fig. 10, 14
$L_E$	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package
$C_{\text{ies}}$	Input Capacitance	—	740	—	pF	$V_{\text{GE}} = 0\text{V}$ $V_{\text{CC}} = 30\text{V}$ See Fig. 7 $f = 1.0\text{MHz}$
$C_{\text{oes}}$	Output Capacitance	—	92	—		
$C_{\text{res}}$	Reverse Transfer Capacitance	—	9.4	—		

**Notes:**

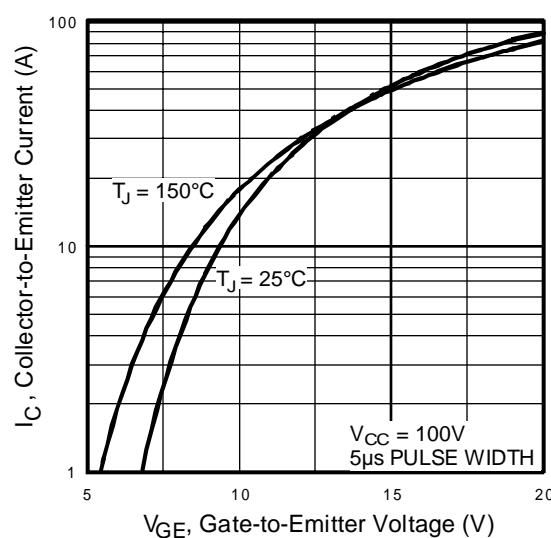
- ① Repetitive rating;  $V_{\text{GE}}=20\text{V}$ , pulse width limited by max. junction temperature.  
( See fig. 13b )
- ②  $V_{\text{CC}}=80\%(V_{\text{CES}})$ ,  $V_{\text{GE}}=20\text{V}$ ,  $L=10\mu\text{H}$ ,  $R_G=23\Omega$ , ( See fig. 13a )
- ③ Repetitive rating; pulse width limited by maximum junction temperature.
- ④ Pulse width  $\leq 80\mu\text{s}$ ; duty factor  $\leq 0.1\%$ .
- ⑤ Pulse width  $5.0\mu\text{s}$ , single shot.



**Fig. 1 - Typical Load Current vs. Frequency**  
(For square wave,  $I=I_{\text{RMS}}$  of fundamental; for triangular wave,  $I=I_{\text{PK}}$ )

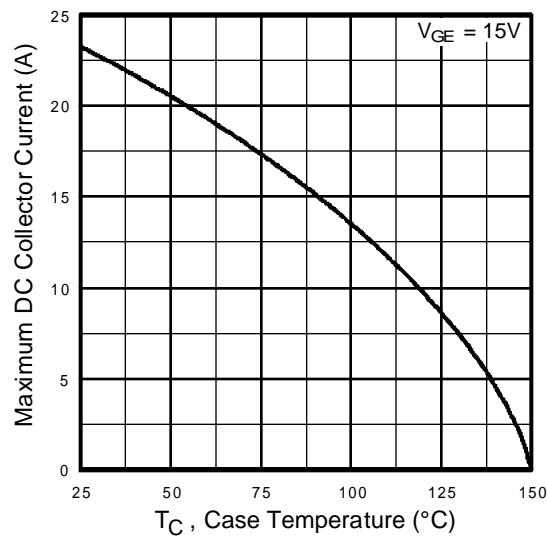


**Fig. 2 - Typical Output Characteristics**

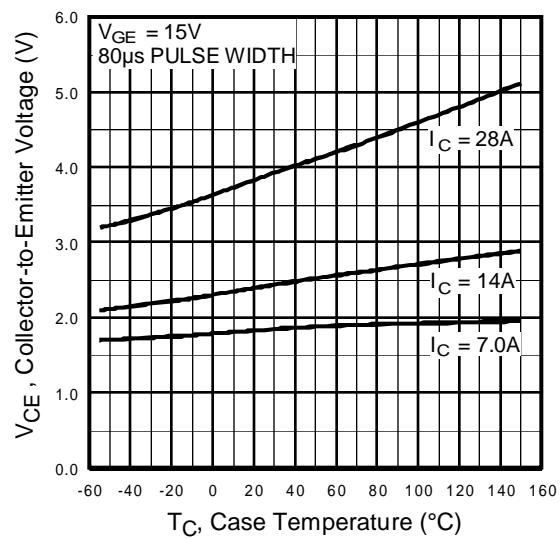


**Fig. 3 - Typical Transfer Characteristics**

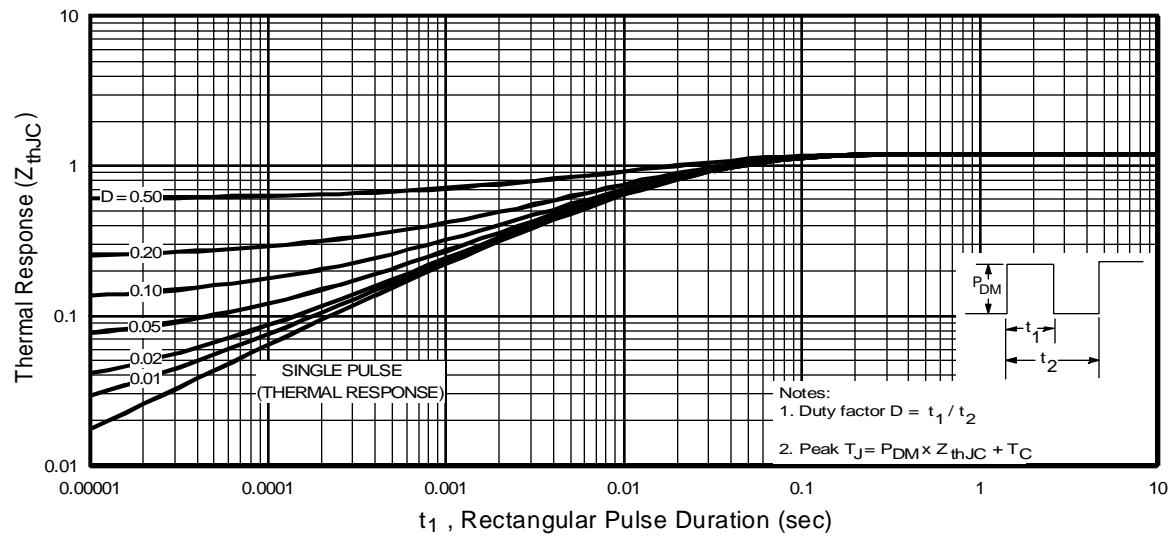
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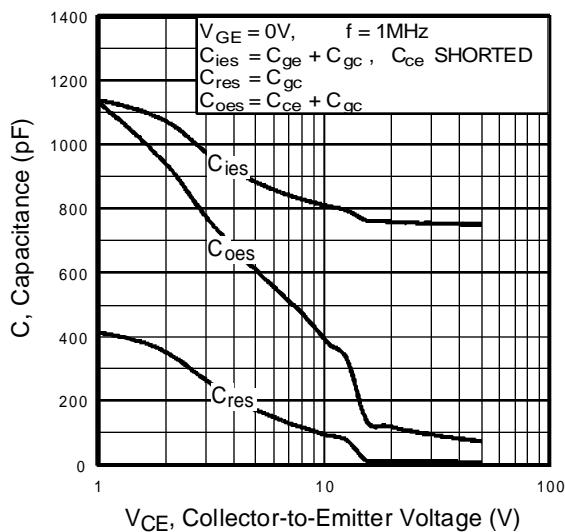
**Fig. 4 - Maximum Collector Current vs. Case Temperature**



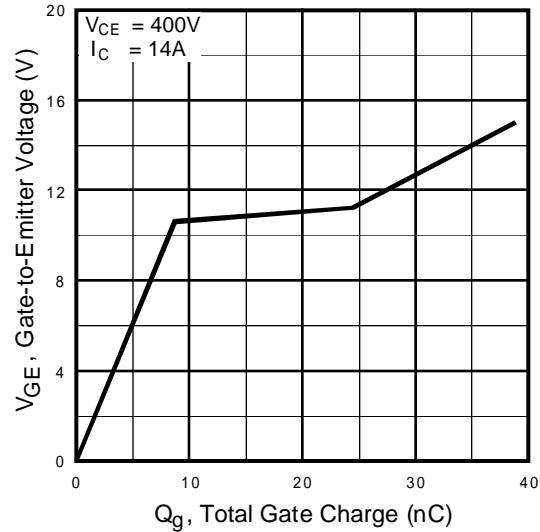
**Fig. 5 - Collector-to-Emitter Voltage vs. Case Temperature**



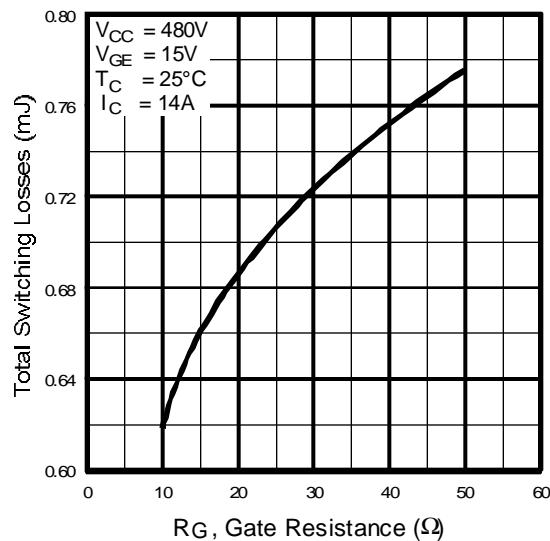
**Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



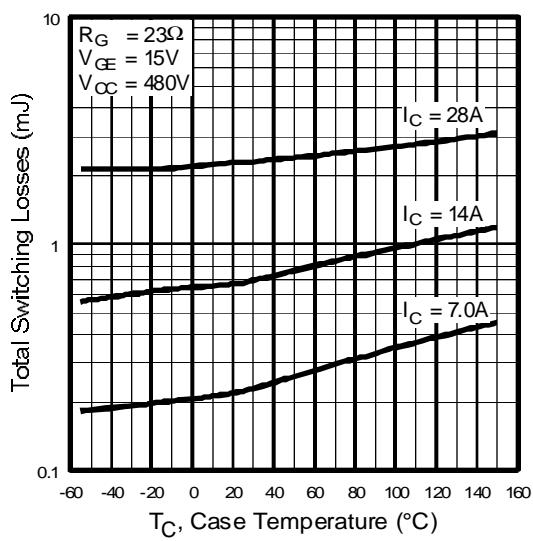
**Fig. 7 - Typical Capacitance vs.  
Collector-to-Emitter Voltage**



**Fig. 8 - Typical Gate Charge vs.  
Gate-to-Emitter Voltage**

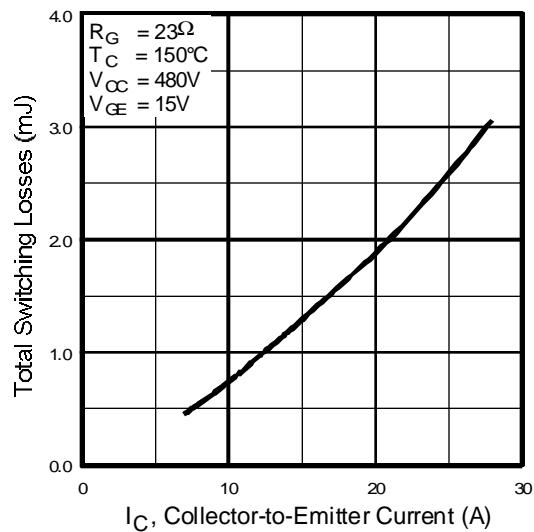


**Fig. 9 - Typical Switching Losses vs. Gate  
Resistance**

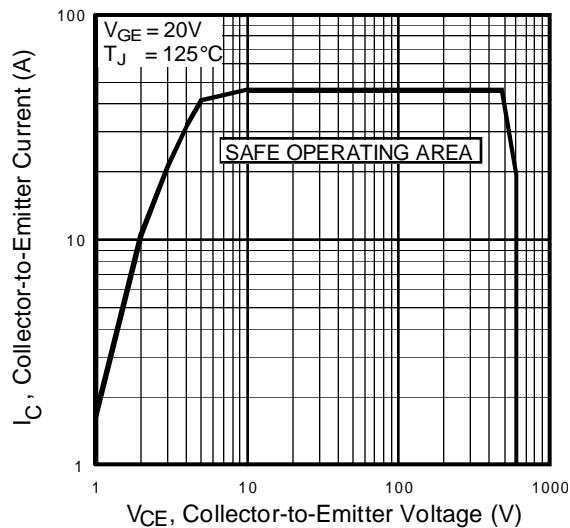


**Fig. 10 - Typical Switching Losses vs.  
Case Temperature**

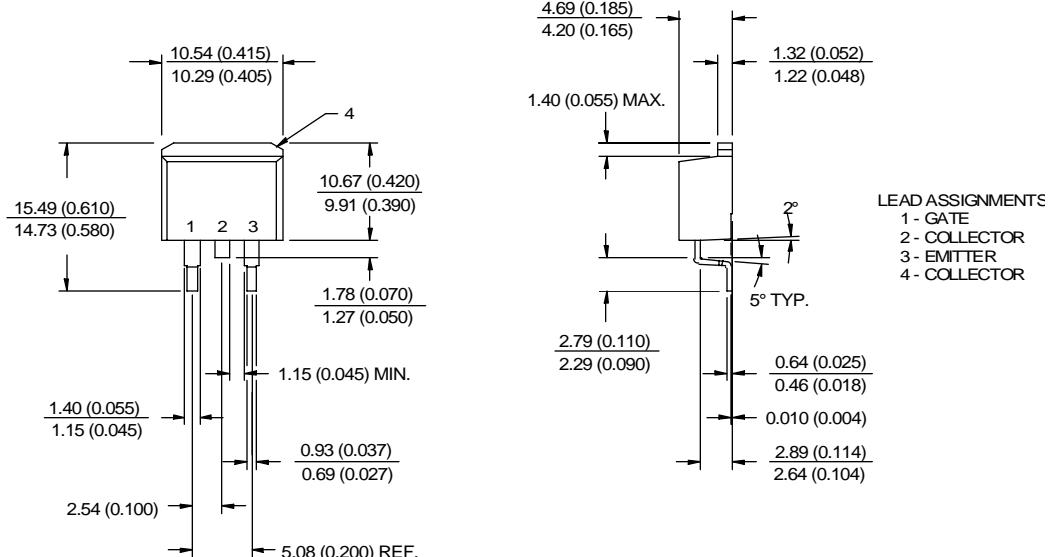
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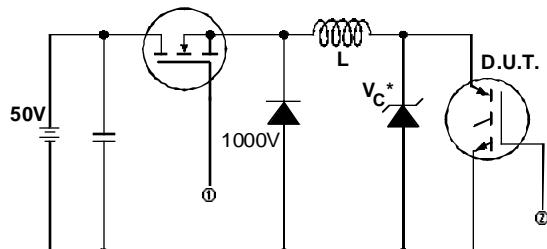
**Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current**



**Fig. 12 - Turn-Off SOA**

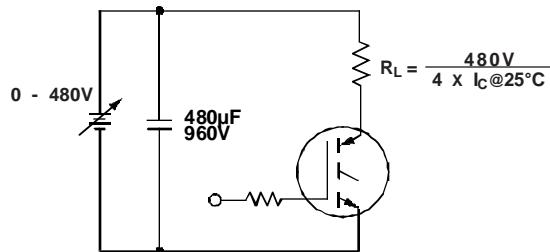


**OUTLINE SMD-220**  
 Dimensions in Millimeters and (Inches)

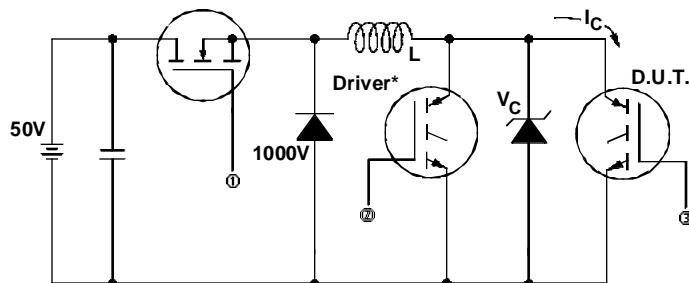


\* Driver same type as D.U.T.;  $V_c = 80\%$  of  $V_{ce(max)}$   
 \* Note: Due to the 50V power supply, pulse width and inductor will increase to obtain rated  $I_d$ .

**Fig. 13a** - Clamped Inductive Load Test Circuit

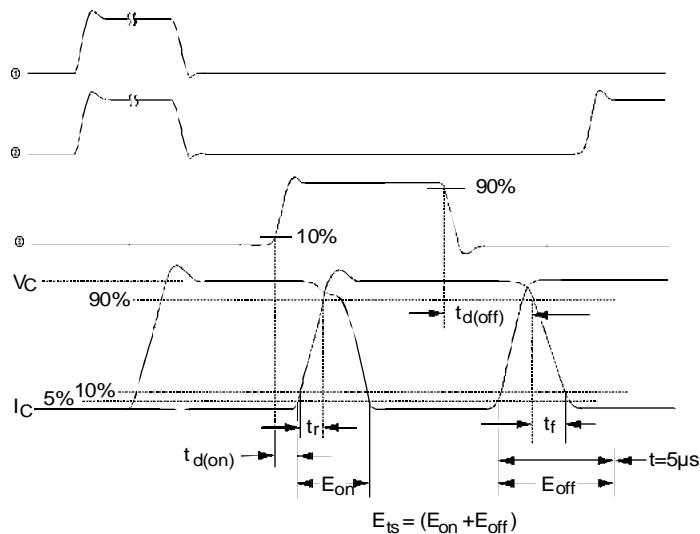


**Fig. 13b** - Pulsed Collector Current Test Circuit



**Fig. 14a** - Switching Loss Test Circuit

\* Driver same type as D.U.T.,  $V_C = \dots$  V



**Fig. 14b** - Switching Loss Waveforms